ABSTRACT OF THE DISCLOSURE

LEAD FRAME AND RESIN PACKAGE AND PHOTOELECTRON DEVICE USING THE SAME

A lead frame includes a die pad including a die pad main portion having a large thickness and a die pad peripheral portion having an intermediate thickness smaller than that of the die pad main portion, provided on at least one side of the die pad main portion, at least one support lead connected to the die pad, and at least two first inner leads having a small thickness smaller than that of the die pad peripheral portion, arranged such that end portions thereof are opposed to the die pad peripheral portion. The thick die pad provides good heat release properties, and reducing the thickness of the leads allows fine pitched leads to be produced. Such a lead frame can be manufactured easily by press stamping after belt-shaped regions having different thickness are formed by rolling.

Figure 1